

## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant : Masaharu Nagai et al. Art Unit : 1795  
 Serial No. : 10/694,986 Examiner : Daborah Chacko Davis  
 Filed : October 29, 2003 Conf. No. : 5334  
 Title : METHOD FOR REMOVING RESIST PATTERN AND METHOD FOR  
 MANUFACTURING SEMICONDUCTOR DEVICE

**MAIL STOP AMENDMENT**

Commissioner for Patents  
 P.O. Box 1450  
 Alexandria, VA 22313-1450

**INFORMATION DISCLOSURE STATEMENT**

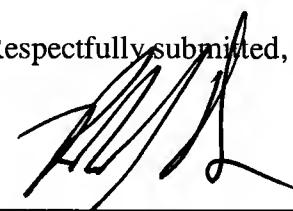
Please consider the references listed on the enclosed PTO-1449 form. Foreign patent documents and non-patent literature are enclosed; cited U.S. patents and patent application publications will be provided on request.

Desig. ID	Source
BA	Japan 01-094342 - English Abstract: esp@cenet database – Worldwide.
BB	Japan 02-084656 – English Abstract: esp@cenet database – Worldwide and family to European Patent No. 0 314 185 (Desig. ID “BN”).
BC	Japan 02-132448 – English Abstract: esp@cenet database – Worldwide.
BD	Japan 02-166178 – English Abstract: esp@cenet database – Worldwide.
BE	Japan 03-053587 – English Abstract: esp@cenet database – Worldwide and family to European Patent No. 0 409 543 (Desig. ID “BO”).
BF	Japan 03-192792 – English Abstract: esp@cenet database – Worldwide.
BG	Japan 10-003169 – English Abstract: esp@cenet database – Worldwide.
BH	Japan 11-176812 – English Abstract: esp@cenet database – Worldwide.
BI	Japan 2000-241992 - English Abstract: esp@cenet database – Worldwide and family to European Patent No. 1 032 026 (Desig. ID “BP”) and U.S. Patent No. 6,734,120 (Desig. ID “AD”).
BJ	Japan 2001-216690 - English Abstract: esp@cenet database – Worldwide.

Desig. ID	Source
BK	Japan 2004-006788 - English Abstract: esp@cenet database – Worldwide and family to U.S. Patent No. 7,344,825 (Desig. ID “AE”) and U.S. Publication No. 2008/0182209 (Desig. ID “AA”).
BL	Japan 2004-517475 - English Abstract: esp@cenet database – Worldwide and family to U.S. Patent No. 6,524,936 (Desig. ID “AC”) and World Office Patent No. 2002/052349 (Desig. ID “BQ”).
BM	Japan 61-086748 - English Abstract: esp@cenet database – Worldwide and family to U.S. Patent No. 4,745,052 (Desig. ID “AB”).

This statement is being filed after a first Office action on the merits, but before receipt of a final Office Action or a Notice of Allowance. Each item of information in this statement, with the exception of references “AA” to “AE” and “BN” to “BQ”, (i) was cited in a communication from a foreign patent office in a counterpart foreign application, the communication being dated March 24, 2009, which is not more than three months prior to the filing of this statement, and (ii) was not first cited in any communication from a foreign patent office in a counterpart application which was more than three months prior to the filing date of this statement. References “AA” to “AE” and “BN” to “BQ” are English-language documents corresponding to references “BB”, “BE”, “BI”, “BK”, “BL” and “BM” as set forth above, and are cited in accordance with MPEP 609.04(b)(V). Please apply any charges or credits to Deposit Account No. 06-1050.

Respectfully submitted,

  
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Date: June 22, 2009

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